



BSI Standards Publication

Circuit boards and circuit board assemblies — Design and use

Part 6-3: Land pattern design — Description of land pattern for through hole components (THT)

National foreword

This British Standard is the UK implementation of EN IEC 61188-6-3:2025. It is identical to IEC 61188-6-3:2024. It partially supersedes BS EN 61188-5-2:2003, BS EN 61188-5-3:2007, BS EN 61188-5-4:2007, BS EN 61188-5-5:2007, BS EN 61188-5-6:2003 and BS EN 61188-5-8:2008.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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